



PATENT

GP/2876
#11A
10/28/02
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re U.S. Patent Application

) Art Unit: 2876

Applicant: Satoshi Kitagawa

)

) I hereby certify that this correspondence is being
deposited with the United States Postal Service
as first class mail in an envelope addressed to:
Commissioner of Patents, Washington, DC 20231,
on October 4, 2002.

Serial No.: 09/696,117

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Filed: October 25, 2000

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For: **MARKING METHOD FOR
SEMICONDUCTOR WAFER**

)

) Gerald T. Shekleton
Gerald T. Shekleton Reg. No. 27,466

Examiner: Karl D. Frech

)

AMENDMENT

Box NON-FEE AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Dear Sir:

The Office Action of February 5, 2002 has been carefully reviewed and the following amendments
and remarks are made in response thereto:

IN THE CLAIMS:

Please amend claims 5, 6, 10, 11, and 17 to 22 as follows:

5. (Amended) The method of reproducing a mark on a semiconductor wafer according
to claim 2, wherein the predetermined mark is formed by means of a combination of dots, each dot
measuring 1 to 13 μ m wide, and the substantially-effaced mark is reproduced by means of forming a
mark essentially identical with the substantially-effaced mark at another location in the vicinity of the

10/23/2002 AUS/ES/0000117 09/696,117

01 TC:1251 110.00 CH (Amended) The method of reproducing a mark on a semiconductor wafer according
to claim 2, wherein the predetermined mark is a minute ID mark which is assigned to the semiconductor
wafer and is formed by means of a combination of dots, each dot measuring 1 to 13 μ m wide, and the
substantially-effaced mark is reproduced by means of forming a mark essentially identical with the
substantially-effaced mark at another location in the vicinity of the substantially-effaced mark.

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